

Customer No.: 31561  
Application No.: 10605,034  
Docket No.: 10231-US-PA

Amendment

FOR THE TITLE

Please amend the title of this application as "CHIP PACKAGE STRUCTURE WITH STIFFENER AND METHOD FOR MANUFACTURING THE SAME".

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**IN THE SPECIFICATION**

**Paragraph [0017]**

**Figs. 2-8Figures 2, 3 and 4-8 are cross-sectional views illustrating the manufacturing steps of the mini BGA package structure according to one preferred embodiment of the present invention.**

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